Abstracts

Membrane-supported Ka band resonator employing organic micromachined packaging

J.E. Harriss, L.W. Pearson, X. Wang, C.H. Barren, Jr. and A.-V. Pham. "Membrane-supported Ka band resonator employing organic micromachined packaging." 2000 MTT-S International Microwave Symposium Digest 00.2 (2000 Vol. II [MWSYM]): 1225-1228.

A scheme for employing organic materials for micromachining of the packaging structure of membrane-supported millimeter wave circuits is described. The format of the packaging follows that devised by Brown, Blondy, and Rebeiz [1999]. The organic micromachining process employs bulk parts patterned photolithographically from Epon(R) SU-8 photoresist adhered to polyimide membranes. Conducting elements are formed by evaporation of gold, followed by electroplating for thickness build up.

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